

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

B.S. Beaman et al.

Serial No.: 09/382,834

Filed: August 25, 1999

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS, TEST PROBE AND METHODS OF USE THEREOF

Date: June 11, 2001

Group Art Unit: 2858

Examiner: V. Nguyen

Docket No.: YO993-028BX

Assistant Commissioner for Patents  
Washington, D.C. 20231

TRANSMITTAL LETTER

Sir:

Attached herewith are copies of the forms PTO 1449 and PTO 892 from the parent applications of the present application and the progeny of the present application. These references are accumulated on the attached PTO 1449 form for the present application.

1. Application Serial Number 08/055,485, filed on April 30, 1993, now Issued as US 5,635,846
2. Application Serial Number 08/754,869, filed on November 22, 1996, now Issued as US 5,821,763, which is a Continuation of Application Serial Number 08/055,485, filed on April 30, 1993
3. Application Serial Number 09/088,394, filed on June 1, 1998, which is a Divisional of Application Serial Number 08/754,869, filed on November 22, 1996

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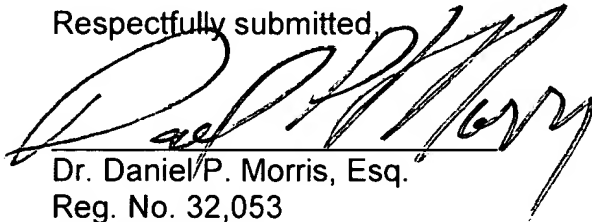
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4. Application Serial Number 08/872,519 filed on June 11, 1997, which is the parent of the present application, which is a Divisional of Application Serial Number 08/754,869 filed on November 22, 1996.

Please charge any fee necessary to enter this paper to deposit account 09-0468.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Daniel P. Morris", is written over a horizontal line.

Dr. Daniel P. Morris, Esq.  
Reg. No. 32,053  
(914) 945-3217

IBM Corporation  
Intellectual Property Law Dept.  
P.O. Box 218  
Yorktown Heights, New York 10598

12. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Buechele et al (Pat # 4,816,754) disclose contactor and probe assembly for electrical test apparatus.


Papae et al (Pat # 5,132,613) disclose low inductance side mount decoupling test structure.

Bove et al (Pat # 4,038,599) disclose high density wafer contacting and test system.

Bove et al (Pat # 3,911,361) disclose coaxial array space transformer.

13. Any inquiry concerning this communication or earlier communications from the examiner should be directed to VINH NGUYEN whose telephone number is (703) 305-4914.

Any inquiry of a general nature or relating to the status of this application should be directed to the Group receptionist whose telephone number is (703) 305-4900.

  
VINH P. NGUYEN  
PRIMARY EXAMINER  
ART UNIT 2607

05/10/94